



SUGGESTED PCB LAYOUT  
(COMPONENT SIDE)

PCB LAYOUT  
TOLERANCE  
.XX±0.05[0.002]

- MATERIALS:  
HOUSING: HIGH TEMP. THERMOPLASTIC, BLACK, UL 94V-0  
CONTACTS: 0.014 INCHES (0.35 MILLIMETERS) THICK PHOSPHOR BRONZE PLATED WITH 150 MICROINCHES (3.81 MICROMETERS) MINIMUM THICK TIN LEAD IN SOLDER AREA. 15 MICROINCHES (0.38 MICROMETERS) MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE CONTACTS PLATED WITH 50 MICROINCHES (1.27 MICROMETERS) MINIMUM THICK NICKEL.  
SHIELDED: 0.0098 INCHES (0.25 MILLIMETERS) THICK COPPER ZINC ALLOY PLATED WITH 30 MICROINCHES (0.762 MICROMETERS) MINIMUM THICK NICKEL.
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F
- PART NUMBER: XRJ-S-01-8-8-X-F2

NOTES: UNLESS OTHERWISE SPECIFIED  
UNSPECIFIED TOLERANCE: .XX ± 0.010 [0.25]  
.X ± 0.006 [0.15]

REFER TO LED OPTIONS TABLE FOR ORDERING CODES

<b>XMULTIPLE</b>		CONNECTING THE INFORMATION PAGE
<small>XMULTIPLE ASIA 8F, No. 80, Jinhua St., Taipei, 10468, Taiwan.</small>	<small>XMULTIPLE USA 8850 Old Conroy Road Newbury Park, CA 91380</small>	<small>DRW: ONE NO. PONS(0712)</small>
THIS DRAWING IS A CONTROLLED DOCUMENT.		
<small>TITLE: RJ45, Connectors, W/LED, 8P, 8C, Shielded, Thru-Hole</small>	<small>DRW: VIQ</small>	<small>DRW: C. TSAI</small>
<small>PART NO: XRJM-S-06-8-8-X-F2</small>	<small>DIMENSIONS mm [inch]</small>	<small>SHEET 1 of 1</small>
<small>REV J</small>	<small>DATE 07/12/01</small>	